



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20251017000.1
Qualification of RFAB as an additional Fab site,
Die Revision and BOM option for select devices
Change Notification / Sample Request

Date: October 17, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20251017000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74LVCZ240APWR	NULL
SN74LVC240APWR	NULL
SN74LVC540APWR	SN74LVC540APWR
SN74LVC541APWR	SN74LVC541APWR
SN74LVCZ244APWR	NULL
SN74LVC244APWRG4	NULL
SN74LVC244APWR	SN74LVC244APWR
SN74LVC541APWRE4	SN74LVC541APWRG4
SN74LVC240APWRG4	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251017000.1		PCN Date:	October 17, 2025																			
Title:	Qualification of RFAB as an additional Fab site, Die Revision and BOM option for select devices																						
Customer Contact:	Change Management Team		Dept:	Quality Services																			
Proposed 1st Ship Date:	January 15, 2026		Sample requests accepted until:	December 16, 2025*																			
*Sample requests received after December 16, 2025 will not be supported.																							
Change Type:																							
<input type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material																		
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process																		
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site																		
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Wafer Fab Material																		
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process																		
PCN Details																							
Description of Change:																							
Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site and BOM option for the devices listed below.																							
<table border="1"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">Additional Fab site</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Additional Fab site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>FFAB</td> <td>ASLC10</td> <td>200mm</td> <td>RFAB</td> <td>LBC9</td> <td>300mm</td> </tr> </tbody> </table>						Current Fab Site			Additional Fab site			Current Fab Site	Process	Wafer Diameter	Additional Fab site	Process	Wafer Diameter	FFAB	ASLC10	200mm	RFAB	LBC9	300mm
Current Fab Site			Additional Fab site																				
Current Fab Site	Process	Wafer Diameter	Additional Fab site	Process	Wafer Diameter																		
FFAB	ASLC10	200mm	RFAB	LBC9	300mm																		
The die was also changed as a result of the process change.																							
Construction differences as follows:																							
<table border="1"> <thead> <tr> <th></th> <th>Current</th> <th>Additional</th> </tr> </thead> <tbody> <tr> <td>Wire diam/type</td> <td>0.96mil Cu</td> <td>0.80mil Cu</td> </tr> </tbody> </table>							Current	Additional	Wire diam/type	0.96mil Cu	0.80mil Cu												
	Current	Additional																					
Wire diam/type	0.96mil Cu	0.80mil Cu																					
Qual details are provided in the Qual Data Section.																							
Reason for Change:																							
Supply Continuity																							
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																							
None																							
Impact on Environmental Ratings																							
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																							
RoHS		REACH		Green Status																			
<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change																			
				IEC 62474																			
				<input checked="" type="checkbox"/> No Change																			
Changes to product identification resulting from this PCN:																							
Fab Site Information:																							
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City																				
FFAB	TID	DEU	Freising																				
RFAB	RFB	USA	Richardson																				

Die Rev:**Current****New**

Die Rev [2P]	Die Rev [2P]
H, J	A

Sample product shipping label (not actual product label):

**Product Affected:**

SN74LVC240APWR	SN74LVC244APWRE4	SN74LVC541APWRG4
SN74LVC240APWRG4	SN74LVC540APWR	SN74LVC541APWRE4
SN74LVC240APWRE4	SN74LVC540APWRE4	SN74LVCZ240APWR
SN74LVC244APWR	SN74LVC540APWRG4	SN74LVCZ244APWR
SN74LVC244APWRG4	SN74LVC541APWR	

Qualification Report

Approve Date 24-June -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74LVC240APWR	Qual Device: SN74LVC541APWR	Qual Device: SN74LVCZ240APWR	QBS Reference: SN74HCS240PWR01	QBS Reference: SN74LV812450PWR01	QBS Reference: SN74LV373APWR01	QBS Reference: SN74LVC7541APWR	QBS Reference: SN74LVC9541APWR	QBS Reference: SN74LVC241APWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	1/77/0	1/77/0	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	3/231/0	-	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	1/77/0	1/77/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0	1/77/0	1/77/0	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/135/0	-	-	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	1/45/0	1/45/0	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/231/0	-	1/77/0	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	1/77/0	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0	-	-	-	-	-
SD	C3	PB Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	-	-	-	1/22	-	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	-	-	-	2/10/0	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	3/30/0	1/10/0	1/10/0	-	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0	1/3/0	1/3/0	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	-	1/3/0	1/6/0	1/6/0	1/6/0	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	3/90/0	3/90/0	1/30/0	1/30	1/30	1/30

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74LVC240APWR is qualified at MSL1 260C

Qual Device SN74LVC541APWR is qualified at MSL1 260C

Qual Device SN74LVCZ240APWR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2408-070

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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